



Product Change Notification: DSNO-18SQTN760

Date:

10-Jun-2026

Product Category:

Switching Regulators

Notification Subject:

CCB 7580 Final Notice: Qualification of ATP7 as an additional assembly site for selected MIC2875 and MIC2876 device families available in 8L UDFN (2x2x0.6mm) package.

Affected CPNs:

[DSNO-18SQTN760_Affected_CPN_06102026.pdf](#)

[DSNO-18SQTN760_Affected_CPN_06102026.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of ATP7 as an additional assembly site for selected MIC2875 and MIC2876 device families available in 8L UDFN (2x2x0.6mm) package.

Pre and Post Summary Changes:

	Pre Change	Post Change		Change (Yes/No)
Assembly Site	Unisem Chengdu Co.,Ltd (UNIC)	Unisem Chengdu Co.,Ltd. (UNIC)	Amkor Technology Philippines (P3/P4), INC. (ATP7)	Yes

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: May 21, 2025: Issued initial notification.

September 03, 2025: Re-issued initial notification to update die-attach material from AP4300 to CDF215.

June 10, 2026: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on July 12, 2026.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_DSNO-18SQTN760_Pre and Post Change Summary.pdf

PCN_DSNO-18SQTN760_Qual Report.pdf

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

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If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN):

MIC2875-AYMT-TR
MIC2875-5.25YMT-TR
MIC2876-5.25YMT-T5
MIC2875-5.5YMT-T5
MIC2876-5.5YMT-T5
MIC2876-4.75YMT-T5
MIC2875-5.25YMT-T5
MIC2875-4.75YMT-T5
MIC2876-AYMT-T5
MIC2876-5.5YMT-TR
MIC2876-5.25YMT-TR
MIC2876-5.0YMT-TR
MIC2876-4.75YMT-TR
MIC2875-AYMT-T5
MIC2875-5.5YMT-TR
MIC2875-5.0YMT-TR
MIC2875-5.0YMT-T5
MIC2875-4.75YMT-TR
MIC2876-5.0YMT-T5
MIC2876-AYMT-TR

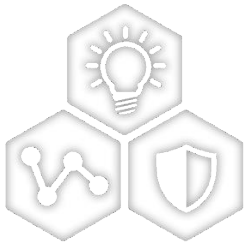
CCB 7580

Pre and Post Change Summary

PCN #: DSNO-18SQTN760

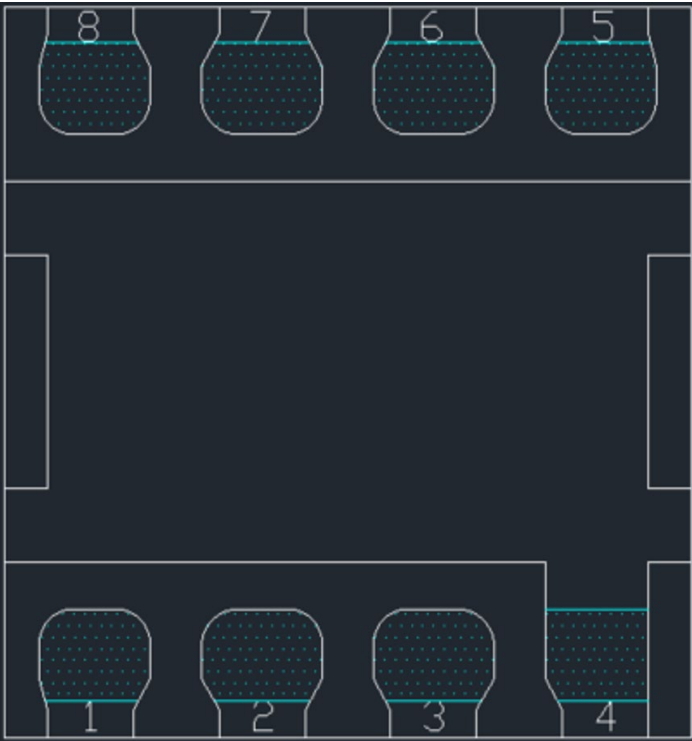
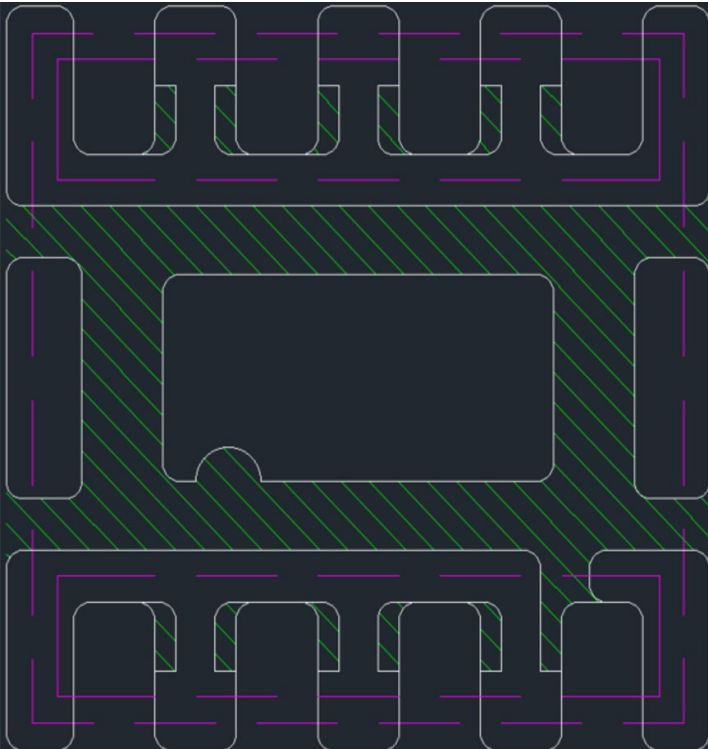


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SMART | CONNECTED | SECURE

Lead-Frame Comparison

UNIC	ATP7												
													
Note: Not-to-scale													
<table><tr><td>Lead-Frame Material</td><td>C194</td></tr><tr><td>DAP Surface Prep</td><td>Spot Ag</td></tr><tr><td>Lead-Frame Paddle Size</td><td>69x41mils</td></tr></table>	Lead-Frame Material	C194	DAP Surface Prep	Spot Ag	Lead-Frame Paddle Size	69x41mils	<table><tr><td>Lead-Frame Material</td><td>C7025</td></tr><tr><td>DAP Surface Prep</td><td>Ring Ag</td></tr><tr><td>Lead-Frame Paddle Size</td><td>67x39mils</td></tr></table>	Lead-Frame Material	C7025	DAP Surface Prep	Ring Ag	Lead-Frame Paddle Size	67x39mils
Lead-Frame Material	C194												
DAP Surface Prep	Spot Ag												
Lead-Frame Paddle Size	69x41mils												
Lead-Frame Material	C7025												
DAP Surface Prep	Ring Ag												
Lead-Frame Paddle Size	67x39mils												



QUALIFICATION REPORT SUMMARY
RELIABILITY LABORATORY

PCN #: DSNO-18SQTN760

Date:
June 08, 2026

**Qualification of ATP7 as an additional assembly site for
selected MIC2875 and MIC2876 device families available in 8L
UDFN (2x2x0.6mm) package.**



MICROCHIP Package Qualification Report

Purpose: Qualification of ATP7 as an additional assembly site for selected MIC2875 and MIC2876 device families available in 8L UDFN (2x2x0.6mm) package.

CCB No. 7580

Misc.	Assembly site	ATP7
	BD Number	BD-003147-03
	MP Code (MPC)	TKNB1YHZAA14
	Part Number (CPN)	MIC2876-5.0YMT-TR
	Assembly Shipping Media (T/R, Tube/Tray)	Cannister
	Base Quantity Multiple (BQM)	3,300
Lead-Frame	Paddle size	67x39mils
	Material	C7025
	DAP Surface Prep	Ring Ag
	Treatment	Rough
	Process	Etch
	Lead-lock	Yes (Half Etch)
	Part Number	101431341
	Lead Plating	MatteSn
	Strip Size	70x250mm
Bond Wire	Strip Density	2496
	Material	CuPdAu
Die Attach	Part Number	CDF215
	Conductive	Yes
MC	Part Number	G631BQF
PKG	PKG Type	UDFN
	Pin/Ball Count	8
	PKG width/size	2x2x0.6mm



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Package Qualification Report

Manufacturing Information:

Assembly Lot No.
ATP7262600011.000
ATP7262600012.000
ATP7262600013.000

Conclusion:

Qualification of TKNB1 mask / MIC2876-5.0YMT-TR product / 1.2 mil CuPdAu wire in 8L UDFN 2x2x0.6mm (HZA) package at ATP7 site is qualified for MSL1 at 260°C as per JEDEC J-STD-020 standard and is passed in accordance to Specified JEDEC and Mil Standards.



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Package Qualification Report

Moisture Soak Precondition Prior to Stresses

Test Method	JESD22-A113, JEDEC J-STD-020		
Test Condition	MSL1: 150°C 24 hours Bake, 168 hours Moisture Soak at 85°C/85%RH, 3x Reflow at 260°C		
Required Sample Size	231 units each lot / 3 lots;		
Lot ID	R2501388-1 ATP7262600011.000	R2501388-2 ATP7262600012.000	R2501388-3 ATP7262600013.000
Electrical Results (Fail / Pass)	0/231	0/231	0/231
Electrical Test Tester: TMT	25°C		
Result	Passed		

High Temp Storage

Test Method	JESD22-A103		
Test Condition	175°C / 504 hours		
Required Sample Size	45 units / 3 lot;		
Lot ID	R2501388-1 ATP7262600011.000	R2501388-2 ATP7262600012.000	R2501388-3 ATP7262600013.000
Electrical Results (Fail / Pass)	0/45	0/45	0/45
Electrical Test Tester: TMT	25°C		
Result	Passed		



MICROCHIP Package Qualification Report

Temperature Cycling

Test Method	JESD22-A104		
Test Condition	-65°C / +150°C Air to Air / 500 Cycles		
Required Sample Size	77 units each lot / 3 lots;		
Lot ID	R2501388-1 ATP7262600011.000	R2501388-2 ATP7262600012.000	R2501388-3 ATP7262600013.000
Electrical Results (Fail / Pass)	0/77	0/77	0/77
WBP (Fail / Pass)	0/5	N/A	N/A
Electrical Test Tester: TMT	25°C		
Result	Passed		

Biased HAST

Test Method	JESD22-A110		
Test Condition	+130°C / 85%RH / 96 hours / Bias Voltage: 5.5V		
Required Sample Size	77 units each lot / 3 lots;		
Lot ID	R2501388-1 ATP7262600011.000	R2501388-2 ATP7262600012.000	R2501388-3 ATP7262600013.000
Electrical Results (Fail / Pass)	0/77	0/77	0/77
Electrical Test Tester: TMT	25°C		
Result	Passed		



MICROCHIP Package Qualification Report

Unbiased HAST

Test Method	JESD22-A118		
Test Condition	+130°C / 85%RH / 96 hours		
Required Sample Size	77 units each lot / 3 lots;		
Lot ID	R2501388-1 ATP7262600011.000	R2501388-2 ATP7262600012.000	R2501388-3 ATP7262600013.000
Electrical Results (Fail / Pass)	0/77	0/77	0/77
Electrical Test Tester: TMT	25°C		
Result	Passed		

Solderability (0 Hr) Method 1: Dip and Look

Test Method	J-STD-002 / JESD22B-102
Test Condition / Criteria	Pb-free 8 hours Steam age. Dip at 245°C, 100% leads >95% lead coverage
Required Sample Size	22 units / 1 lot
Visual Result (Fail / Pass)	0/22
Result	Passed

Physical Dimension (0Hr)

Test Method	JESD22 B100 and B108
Test Criteria	Within package diagram dimension
Required Sample Size	10 units each lot / 3 lots
Result (Fail / Pass)	0/30 – Passed



MICROCHIP
Package Qualification Report
Wire Pull

Test Method	Mil. Std. 883-2011
Test Criteria	Bond Strength Data Assembly
Required Sample Size	5 units / 1 lot
Result (Fail / Pass)	0/5 - Passed

Bond Shear

Test Method	CDF-AEC-Q100-001
Test Criteria	Bond Strength Data Assembly
Required Sample Size	5 units / 1 lot
Result (Fail / Pass)	0/5 - Passed

Bond Line Thickness

Test Method	SPI-45528
Test Criteria	0.60-1.50mils
Required Sample Size	5 units each lot / 3 lots
Result (Fail / Pass)	0/15 - Passed

Wire sweep

Test Method	X-ray
Test Criteria	15%
Required Sample Size	15 wires each lot / 3 lots
Result (Fail / Pass)	0/45 – Passed